
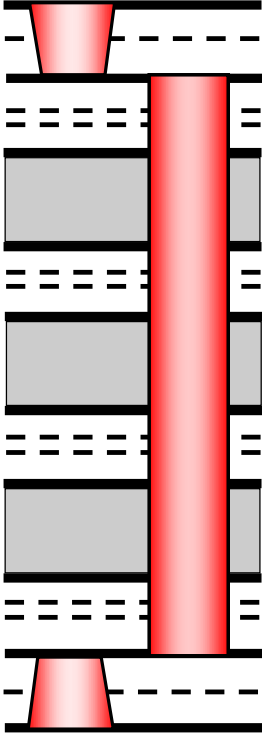


Build Up HDI (Standard)														
HDI10_1+8b+1_1,15_17.5_engl			10 - Layers							Core: 0,10 mm Cu 17.5/17.5 µm				
WE-Article No.:		1 + 8B + 1												
Customer:														
layer description		configuration			Raw-Material	CU	PREPREG	Final Thickness	Customer requirements					
Customer	WE							[µm]	[µm]					
	TOP/VS				Foil	12 µm	1)	12						
									1 x 1080	60				
	2				Foil	9 µm		30						
									2 x 1080	140				
	3					17.5 µm		16						
					0,100 mm			100						
	4					17.5 µm		16						
									2 x 1080	134				
	5					17.5 µm		16						
		0,100 mm			100									
	6		17.5 µm		16									
						2 x 1080	134							
	7		17.5 µm		16									
		0,100 mm			100									
	8		17.5 µm		16									
						2 x 1080	140							
	9		17.5 µm		16									
		0,100 mm			100									
	BOT/RS	Foil	9 µm		30									
						1 x 1080	60							
		Foil	12 µm	1)	12									
					1) copper thickness outer layers: appr. 55 µm									
					total material thickness: 1148									
					Note: Lamination thickness for Prepregs depending on layout characteristics.									
final lamination thickness:		1,15	+/-	0,09	mm	Date:		Engineer:						
thickness with electro plated Cu:		1,24	+/-	0,12	mm									
total thickness with soldermask		1,30	+/-	0,14	mm									
customer requirement			+/-		mm	point:								
prepared: on 27.03.2006 by S. Keller		checked: on 04.05.2006 by M.Kress		approved: on 04.05.2006 by R.Schönholz		revision 00		page: 14+						